Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	32256
Number of Logic Elements/Cells	-
Total RAM Bits	294912
Number of I/O	586
Number of Gates	2000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	896-BGA
Supplier Device Package	896-FBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax2000-1fg896

Up to four individual signals can be brought out to dedicated probe pins (PRA/B/C/D) on the device. The probe circuitry is accessed and controlled via Silicon Explorer II, Microsemi's integrated verification and logic analysis tool that attaches to the serial port of a PC and communicates with the FPGA via the JTAG port (See "Silicon Explorer II Probe Interface" on page 2-109).

Summary

Microsemi's Axcelerator family of FPGAs extends the successful SX-A architecture, adding embedded RAM/FIFOs, PLLs, and high-speed I/Os. With the support of a suite of robust software tools, design engineers can incorporate high gate counts and fixed pins into an Axcelerator design yet still achieve high performance and efficient device utilization.

Related Documents

Application Notes

Simultaneous Switching Noise and Signal Integrity
http://www.microsemi.com/soc/documents/SSN_AN.pdf
Axcelerator Family PLL and Clock Management
http://www.microsemi.com/soc/documents/AX_PLL_AN.pdf
Implementation of Security in Actel Antifuse FPGAs
http://www.microsemi.com/soc/documents/Antifuse_Security_AN.pdf

User's Guides and Manuals

Antifuse Macro Library Guide
http://www.microsemi.com/soc/documents/libguide_UG.pdf
SmartGen, FlashROM, Analog System Builder, and Flash Memory System Builder
http://www.microsemi.com/soc/documents/genguide_ug.pdf
Silicon Sculptor II User's Guide
http://www.microsemi.com/soc/documents/silisculptII_sculpt3_ug.pdf

White Paper

Design Security in Nonvolatile Flash and Antifuse FPGAs
http://www.microsemi.com/soc/documents/DesignSecurity_WP.pdf
Understanding Actel Antifuse Device Security
http://www.microsemi.com/soc/documents/DesignSecurity_WP.pdf

Miscellaneous

Libero IDE flow diagram
http://www.microsemi.com/soc/products/tools/libero/flow.html

User-Defined Supply Pins

VREF **Supply Voltage**

Reference voltage for I/O banks. VREF pins are configured by the user from regular I/O pins; VREF pins are not in fixed locations. There can be one or more VREF pins in an I/O bank.

Global Pins

HCLKA/B/C/D **Dedicated (Hardwired) Clocks A, B, C and D**

These pins are the clock inputs for sequential modules or north PLLs. Input levels are compatible with all supported I/O standards. There is a P/N pin pair for support of differential I/O standards. Single-ended clock I/Os can only be assigned to the P side of a paired I/O. This input is directly wired to each R-cell and offers clock speeds independent of the number of R-cells being driven. When the HCLK pins are unused, it is recommended that they are tied to ground.

CLKE/F/G/H **Routed Clocks E, F, G, and H**

These pins are clock inputs for clock distribution networks or south PLLs. Input levels are compatible with all supported I/O standards. There is a P/N pin pair for support of differential I/O standards. Single-ended clock I/Os can only be assigned to the P side of a paired I/O. The clock input is buffered prior to clocking the R-cells. When the CLK pins are unused, Microsemi recommends that they are tied to ground.

JTAG/Probe Pins

PRA/B/C/D **Probe A, B, C and D**

The Probe pins are used to output data from any user-defined design node within the device (controlled with Silicon Explorer II). These independent diagnostic pins can be used to allow real-time diagnostic output of any signal path within the device. The pins' probe capabilities can be permanently disabled to protect programmed design confidentiality. The probe pins are of LVTTL output levels.

TCK **Test Clock**

Test clock input for JTAG boundary-scan testing and diagnostic probe (Silicon Explorer II).

TDI **Test Data Input**

Serial input for JTAG boundary-scan testing and diagnostic probe. TDI is equipped with an internal 10 kΩ pull-up resistor.

TDO **Test Data Output**

Serial output for JTAG boundary-scan testing.

TMS **Test Mode Select**

The TMS pin controls the use of the IEEE 1149.1 boundary-scan pins (TCK, TDI, TDO, TRST). TMS is equipped with an internal 10 kΩ pull-up resistor.

TRST **Boundary Scan Reset Pin**

The TRST pin functions as an active-low input to asynchronously initialize or reset the boundary scan circuit. The TRST pin is equipped with a 10 kΩ pull-up resistor.

Special Functions

LP **Low Power Pin**

The LP pin controls the low power mode of Axcelerator devices. The device is placed in the low power mode by connecting the LP pin to logic high. To exit the low power mode, the LP pin must be set Low. Additionally, the LP pin must be set Low during chip powering-up or chip powering-down operations. See "Low Power Mode" on page 2-106 for more details.

NC **No Connection**

This pin is not connected to circuitry within the device. These pins can be driven to any voltage or can be left floating with no effect on the operation of the device.

Table 2-8 • **I/O Standards Supported by the Axcelerator Family**

I/O Standard	Input/Output Supply Voltage (VCCI)	Input Reference Voltage (VREF)	Board Termination Voltage (VTT)
LVTTL	3.3	N/A	N/A
LVCMOS 2.5 V	2.5	N/A	N/A
LVCMOS 1.8 V	1.8	N/A	N/A
LVCMOS 1.5 V (JDEC8-11)	1.5	N/A	N/A
3.3V PCI/PCI-X	3.3	N/A	N/A
GTL+ 3.3 V	3.3	1.0	1.2
GTL+ 2.5 V*	2.5	1.0	1.2
HSTL Class 1	1.5	0.75	0.75
SSTL3 Class 1 and II	3.3	1.5	1.5
SSTL2 Class1 and II	2.5	1.25	1.25
LVDS	2.5	N/A	N/A
LVPECL	3.3	N/A	N/A

*Note: *2.5 V GTL+ is not supported across the full military temperature range.*

Table 2-9 • **Supply Voltages**

VCCA	VCCI	Input Tolerance	Output Drive Level
1.5 V	1.5 V	3.3 V	1.5 V
1.5 V	1.8 V	3.3 V	1.8 V
1.5 V	2.5 V	3.3 V	2.5 V
1.5 V	3.3 V	3.3 V	3.3 V

Table 2-10 • **I/O Features Comparison**

I/O Assignment	Clamp Diode	Hot Insertion	5 V Tolerance	Input Buffer	Output Buffer
LVTTL	No	Yes	Yes[1]	Enabled/Disabled	
3.3 V PCI, 3.3 V PCI-X	Yes	No	Yes[1, 2]	Enabled/Disabled	
LVCMOS 2.5 V	No	Yes	No	Enabled/Disabled	
LVCMOS 1.8 V	No	Yes	No	Enabled/Disabled	
LVCMOS 1.5 V (JESD8-11)	No	Yes	No	Enabled/Disabled	
Voltage-Referenced Input Buffer	No	Yes	No	Enabled/Disabled	
Differential, LVDS/LVPECL, Input	No	Yes	No	Enabled	Disabled[3]
Differential, LVDS/LVPECL, Output	No	Yes	No	Disabled	Enabled[4]

Notes:

1. *Can be implemented with an IDT bus switch.*
2. *Can be implemented with an external resistor.*
3. *The OE input of the output buffer must be deasserted permanently (handled by software).*
4. *The OE input of the output buffer must be asserted permanently (handled by software).*

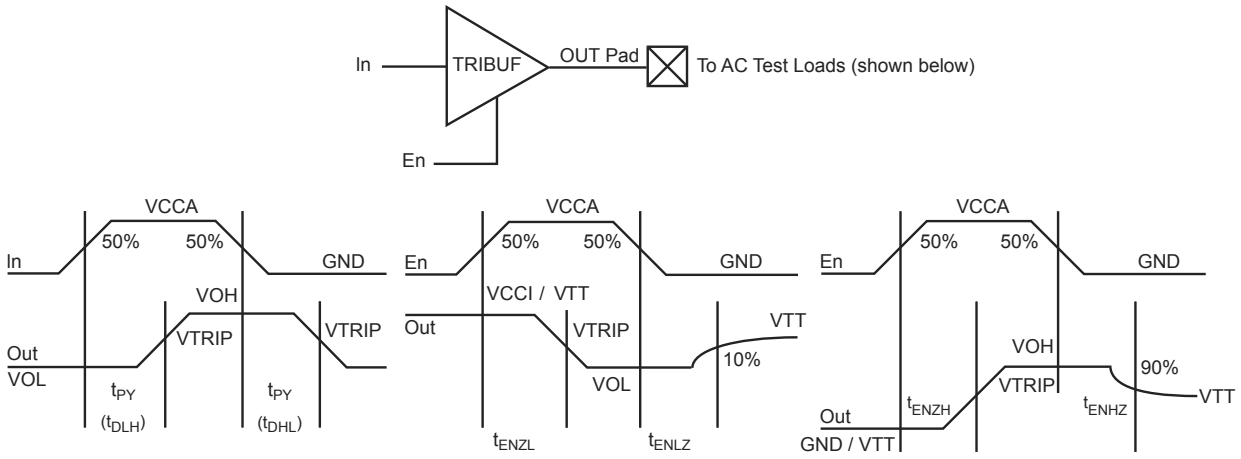


Figure 2-10 • **Output Buffer Delays**

Buffer Module

Introduction

An additional resource inside each SuperCluster is the Buffer (B) module (Figure 1-4 on page 1-3). When a fanout constraint is applied to a design, the synthesis tool inserts buffers as needed. The buffer module has been added to the AX architecture to avoid logic duplication resulting from the hard fanout constraints. The router utilizes this logic resource to save area and reduce loading and delays on medium-to-high-fanout nets.

Timing Models and Waveforms

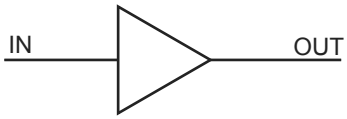


Figure 2-33 • **Buffer Module Timing Model**

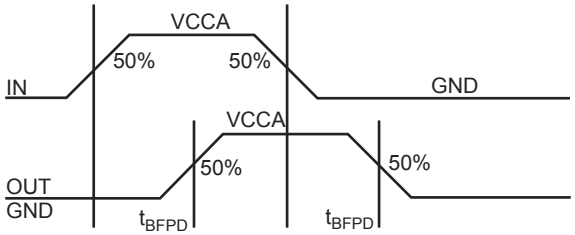


Figure 2-34 • **Buffer Module Waveform**

Timing Characteristics

Table 2-64 • **Buffer Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Buffer Module Propagation Delays								
t_{BFPD}	Any input to output Y		0.12		0.14		0.16	ns

***Table 2-77* • AX500 Routed Array Clock Networks**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Routed Array Clock Networks								
t_{RCKL}	Input Low to High		2.31		2.63		3.09	ns
t_{RCKH}	Input High to Low		2.44		2.78		3.27	ns
t_{RPWH}	Minimum Pulse Width High	0.57		0.64		0.75		ns
t_{RPWL}	Minimum Pulse Width Low	0.52		0.59		0.69		ns
t_{RCKSW}	Maximum Skew		0.35		0.39		0.46	ns
t_{RP}	Minimum Period	1.15		1.31		1.54		ns
t_{RMAX}	Maximum Frequency		870		763		649	MHz

***Table 2-78* • AX1000 Routed Array Clock Networks**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Routed Array Clock Networks								
t_{RCKL}	Input Low to High		3.08		3.50		4.12	ns
t_{RCKH}	Input High to Low		3.13		3.56		4.19	ns
t_{RPWH}	Minimum Pulse Width High	0.57		0.64		0.75		ns
t_{RPWL}	Minimum Pulse Width Low	0.52		0.59		0.69		ns
t_{RCKSW}	Maximum Skew		0.35		0.39		0.46	ns
t_{RP}	Minimum Period	1.15		1.31		1.54		ns
t_{RMAX}	Maximum Frequency		870		763		649	MHz

***Table 2-79* • AX2000 Routed Array Clock Networks**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

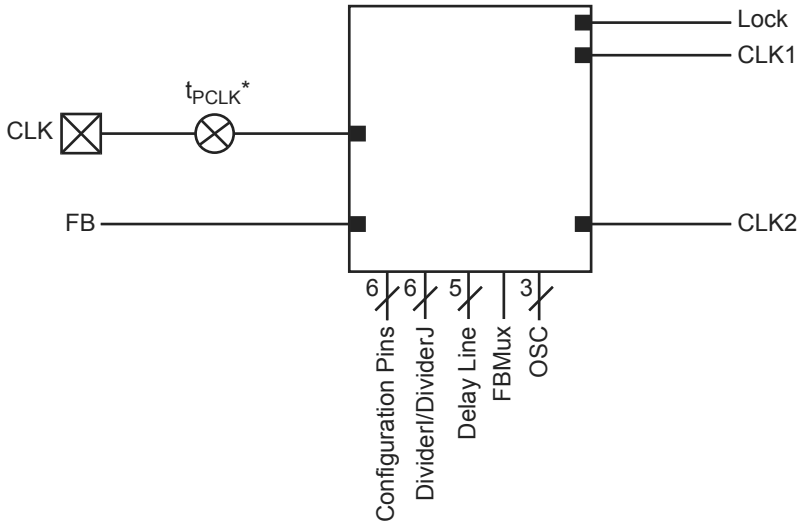
		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Routed Array Clock Networks								
t_{RCKL}	Input Low to High		3.08		3.50		4.12	ns
t_{RCKH}	Input High to Low		3.13		3.56		4.19	ns
t_{RPWH}	Minimum Pulse Width High	0.57		0.64		0.75		ns
t_{RPWL}	Minimum Pulse Width Low	0.52		0.59		0.69		ns
t_{RCKSW}	Maximum Skew		0.35		0.39		0.46	ns
t_{RP}	Minimum Period	1.15		1.31		1.54		ns
t_{RMAX}	Maximum Frequency		870		763		649	MHz

User Flow

There are two methods of including a PLL in a design:

- The recommended method of using a PLL is to create custom PLL blocks using Microsemi's macro generator, SmartGen, that can be instantiated in a design.
- The alternative method is to instantiate one of the generic library primitives (PLL or PLLFB) into either a schematic or HDL netlist, using inverters for polarity control and tying all unused address and data bits to ground.

Timing Model



Note: t_{PCLK} is the delay in the clock signal

Figure 2-52 • **PLL Model**

Note that the RAM blocks employ little-endian byte order for read and write operations.

***Table 2-88* • RAM Signal Description**

Signal	Direction	Description
WCLK	Input	Write clock (can be active on either edge).
WA[J:0]	Input	Write address bus.The value J is dependent on the RAM configuration and the number of cascaded memory blocks. The valid range for J is from 6 to15.
WD[M-1:0]	Input	Write data bus. The value M is dependent on the RAM configuration and can be 1, 2, 4, 9, 18, or 36.
RCLK	Input	Read clock (can be active on either edge).
RA[K:0]	Input	Read address bus. The value K is dependent on the RAM configuration and the number of cascaded memory blocks. The valid range for K is from 6 to 15.
RD[N-1:0]	Output	Read data bus. The value N is dependent on the RAM configuration and can be 1, 2, 4, 9, 18, or 36.
REN	Input	Read enable. When this signal is valid on the active edge of the clock, data at location RA will be driven onto RD.
WEN	Input	Write enable. When this signal is valid on the active edge of the clock, WD data will be written at location WA.
RW[2:0]	Input	Width of the read operation dataword.
WW[2:0]	Input	Width of the write operation dataword.
Pipe	Input	Sets the pipe option to be on or off.

Modes of Operation

There are two read modes and one write mode:

- Read Nonpipelined (synchronous – one clock edge)
- Read Pipelined (synchronous – two clock edges)
- Write (synchronous – one clock edge)

In the standard read mode, new data is driven onto the RD bus in the clock cycle immediately following RA and REN valid. The read address is registered on the read-port active-clock edge and data appears at read-data after the RAM access time. Setting the PIPE to OFF enables this mode.

The pipelined mode incurs an additional clock delay from address to data, but enables operation at a much higher frequency. The read-address is registered on the read-port active-clock edge, and the read data is registered and appears at RD after the second read clock edge. Setting the PIPE to ON enables this mode.

On the write active-clock edge, the write data are written into the SRAM at the write address when WEN is high. The setup time of the write address, write enables, and write data are minimal with respect to the write clock.

Write and read transfers are described with timing requirements beginning in the "Timing Characteristics" section on page 2-89.

Timing Characteristics

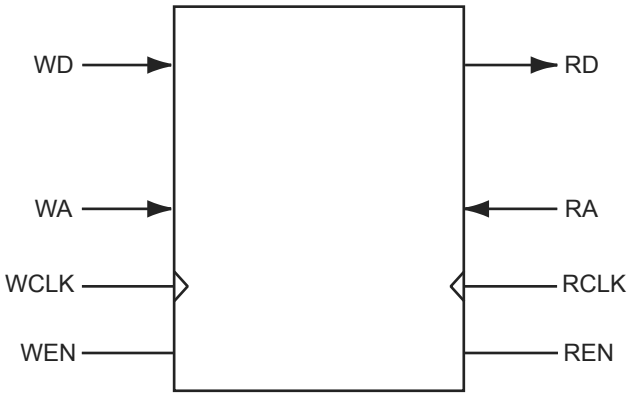


Figure 2-58 • **SRAM Model**

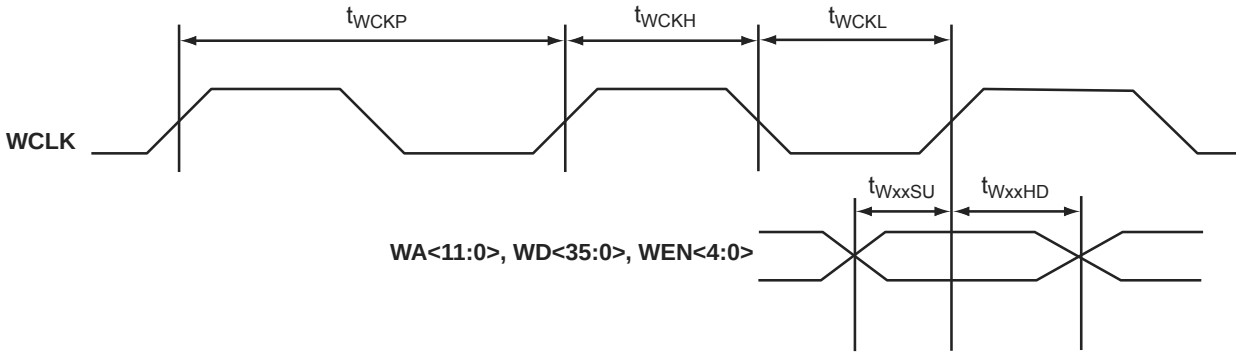


Figure 2-59 • **RAM Write Timing Waveforms**

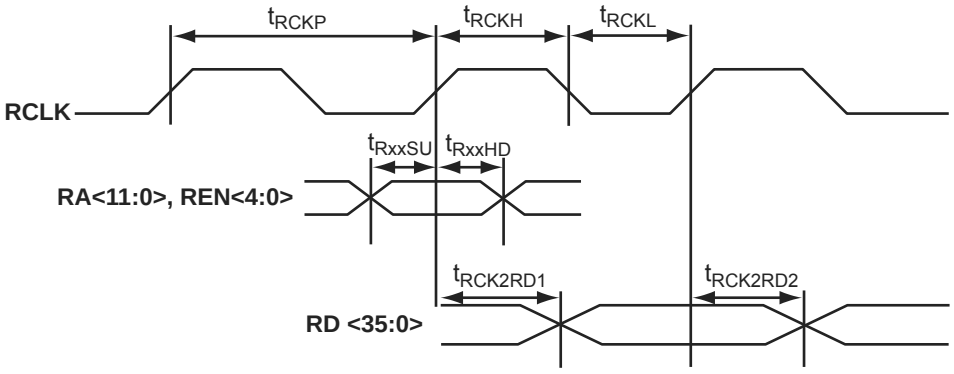


Figure 2-60 • **RAM Read Timing Waveforms**

Programming

Device programming is supported through the Silicon Sculptor II, a single-site, robust and compact device programmer for the PC. Up to four Silicon Sculptor IIs can be daisy-chained and controlled from a single PC host. With standalone software for the PC, Silicon Sculptor II is designed to allow concurrent programming of multiple units from the same PC when daisy-chained.

Silicon Sculptor II programs devices independently to achieve the fastest programming times possible. Each fuse is verified by Silicon Sculptor II to ensure correct programming. Furthermore, at the end of programming, there are integrity tests that are run to ensure that programming was completed properly. Not only does it test programmed and nonprogrammed fuses, Silicon Sculptor II also provides a self-test to test its own hardware extensively.

Programming an Axcelerator device using Silicon Sculptor II is similar to programming any other antifuse device. The procedure is as follows:

1. Load the *.AFM file.
2. Select the device to be programmed.
3. Begin programming.

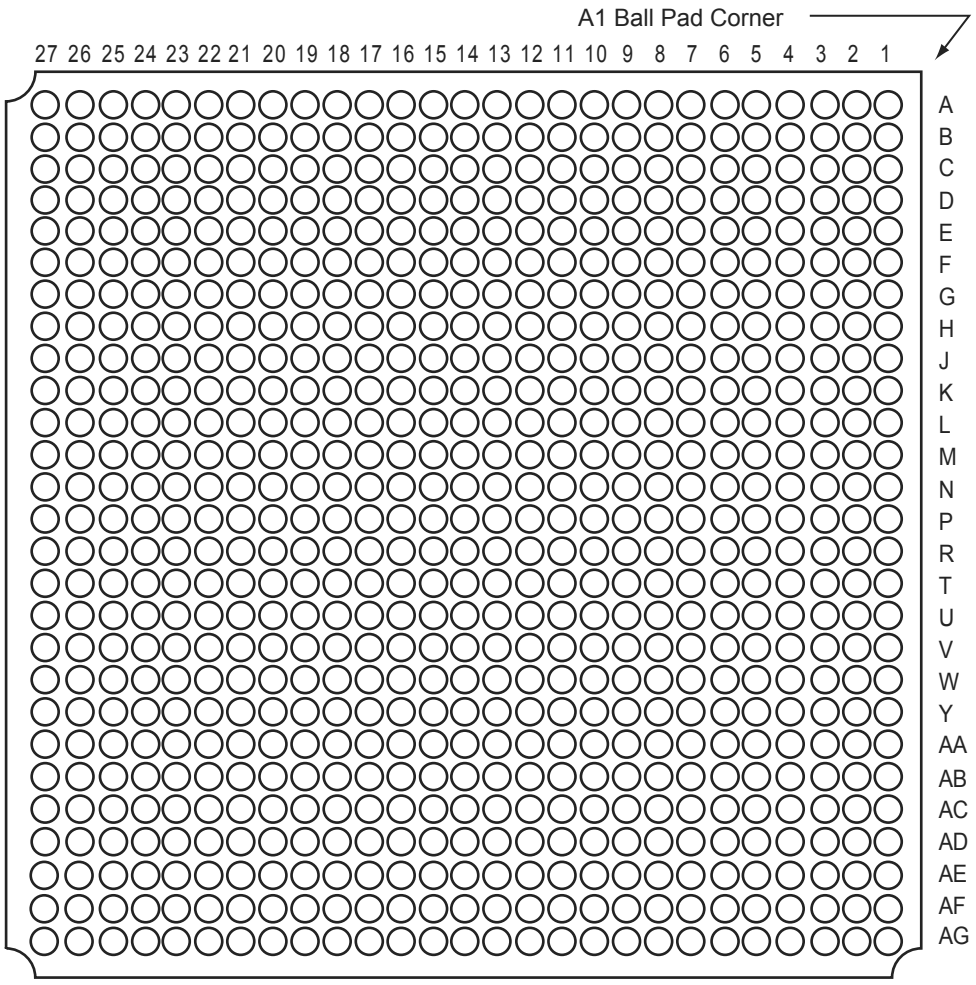
When the design is ready to go to production, Microsemi offers device volume-programming services either through distribution partners or via our In-House Programming Center.

In addition, BP Microsystems offers multi-site programmers that provide qualified support for Axcelerator devices.

For more details on programming the Axcelerator devices, please refer to the *Silicon Sculptor II User's Guide*.

3 – Package Pin Assignments

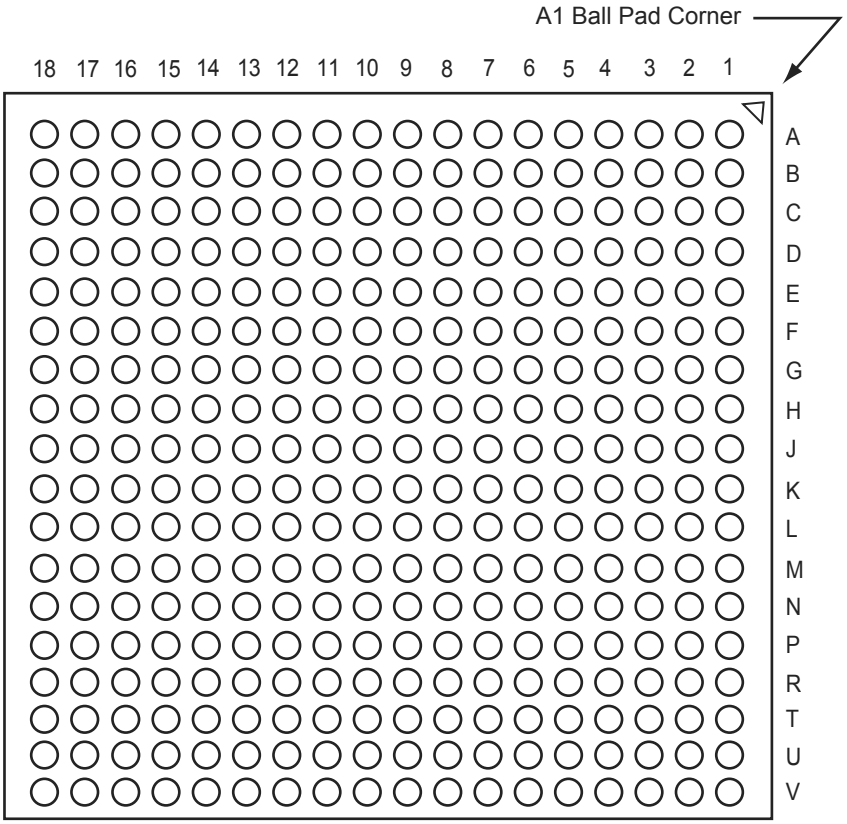
BG729



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG324



Note

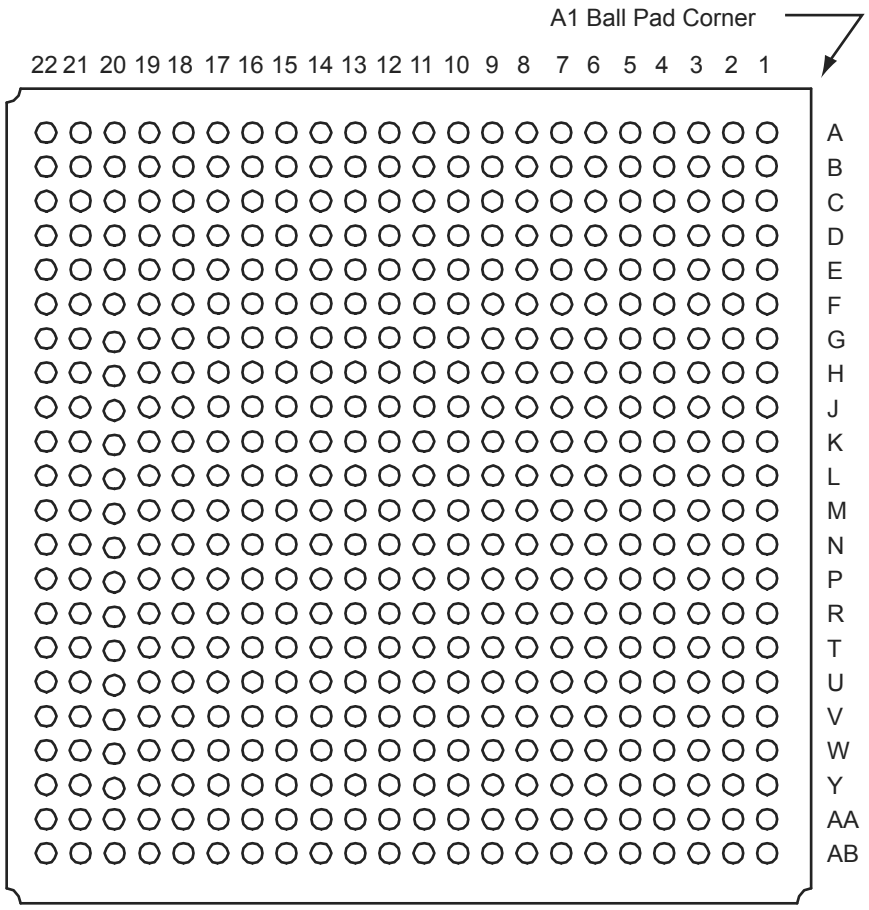
For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG324	
AX125 Function	Pin Number
Bank 0	
IO00NB0F0	C5
IO00PB0F0	C4
IO01NB0F0	A3
IO01PB0F0	A2
IO02NB0F0	C7
IO02PB0F0	C6
IO03NB0F0	B5
IO03PB0F0	B4
IO04NB0F0	A5
IO04PB0F0	A4
IO05NB0F0	A7
IO05PB0F0	A6
IO06NB0F0	B7
IO06PB0F0	B6
IO07NB0F0/HCLKAN	C9
IO07PB0F0/HCLKAP	C8
IO08NB0F0/HCLKBN	B10
IO08PB0F0/HCLKBP	B9
Bank 1	
IO09NB1F1/HCLKCN	D11
IO09PB1F1/HCLKCP	D10
IO10NB1F1/HCLKDN	C12
IO10PB1F1/HCLKDP	C11
IO11NB1F1	A15
IO11PB1F1	A14
IO12NB1F1	B14
IO12PB1F1	B13
IO13NB1F1	A17
IO13PB1F1	A16
IO14NB1F1	D13
IO14PB1F1	D12
IO15NB1F1	C14
IO15PB1F1	C13
IO16NB1F1	B16

FG324	
AX125 Function	Pin Number
IO16PB1F1	C15
IO17NB1F1	E14
IO17PB1F1	E13
Bank 2	
IO18NB2F2	G14
IO18PB2F2	F14
IO19NB2F2	D16
IO19PB2F2	D15
IO20NB2F2	C18
IO20PB2F2	B18
IO21NB2F2	D17
IO21PB2F2	C17
IO22NB2F2	F17
IO22PB2F2	E17
IO23NB2F2	G16
IO23PB2F2	F16
IO24NB2F2	E18
IO24PB2F2	D18
IO25NB2F2	G18
IO25PB2F2	F18
IO26NB2F2	H17
IO26PB2F2	G17
IO27NB2F2	J16
IO27PB2F2	H16
IO28NB2F2	J18
IO28PB2F2	H18
IO29NB2F2	K17
IO29PB2F2	J17
Bank 3	
IO30NB3F3	N18
IO30PB3F3	M18
IO31NB3F3	L18
IO31PB3F3	K18
IO32NB3F3	L16
IO32PB3F3	L17

FG324	
AX125 Function	Pin Number
IO33NB3F3	R18
IO33PB3F3	P18
IO34NB3F3	N15
IO34PB3F3	M15
IO35NB3F3	M16
IO35PB3F3	M17
IO36NB3F3	P16
IO36PB3F3	N16
IO37NB3F3	R17
IO37PB3F3	P17
IO38NB3F3	N14
IO38PB3F3	M14
IO39NB3F3	U18
IO39PB3F3	T18
IO40NB3F3	R16
IO40PB3F3	T17
IO41NB3F3	P13
IO41PB3F3	P14
Bank 4	
IO42NB4F4	T13
IO42PB4F4	T14
IO43NB4F4	U15
IO43PB4F4	T15
IO44NB4F4	U13
IO44PB4F4	U14
IO45NB4F4	V15
IO45PB4F4	V16
IO46NB4F4	V13
IO46PB4F4	V14
IO47NB4F4	V12
IO47PB4F4	U12
IO48NB4F4	V10
IO48PB4F4	V11
IO49NB4F4/CLKEN	T10
IO49PB4F4/CLKEP	T11

FG484



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG484	
AX250 Function	**Pin Number**
IO104PB6F6	N4
IO105NB6F6	M5
IO105PB6F6	N5
IO106NB6F6	M3
IO106PB6F6	N3
Bank 7	
IO107NB7F7	M2
IO107PB7F7	N1
IO108NB7F7	L3
IO108PB7F7	L2
IO109NB7F7	K2
IO109PB7F7	K1
IO110NB7F7	K5
IO110PB7F7	L5
IO111NB7F7	K6
IO111PB7F7	L6
IO112NB7F7	K4
IO112PB7F7	K3
IO113NB7F7	K7
IO113PB7F7	L7
IO114NB7F7	H1
IO114PB7F7	J1
IO115NB7F7	H2
IO115PB7F7	J2
IO116NB7F7	H4
IO116PB7F7	J4
IO117NB7F7	H5
IO117PB7F7	J5
IO118NB7F7	F2
IO118PB7F7	G2
IO119NB7F7	H6
IO119PB7F7	J6
IO120NB7F7	F1
IO120PB7F7	G1
IO121NB7F7	F4
IO121PB7F7	G4

FG484	
AX250 Function	**Pin Number**
IO122NB7F7	G5
IO122PB7F7	G6
IO123NB7F7	F5
IO123PB7F7	E4
Dedicated I/O	
VCCDA	H7
GND	A1
GND	A11
GND	A12
GND	A2
GND	A21
GND	A22
GND	AA1
GND	AA2
GND	AA21
GND	AA22
GND	AB1
GND	AB11
GND	AB12
GND	AB2
GND	AB21
GND	AB22
GND	B1
GND	B2
GND	B21
GND	B22
GND	C20
GND	C3
GND	D19
GND	D4
GND	E18
GND	E5
GND	G18
GND	H15
GND	H8
GND	J14

FG484	
AX250 Function	**Pin Number**
GND	J9
GND	K10
GND	K11
GND	K12
GND	K13
GND	L1
GND	L10
GND	L11
GND	L12
GND	L13
GND	L22
GND	M1
GND	M10
GND	M11
GND	M12
GND	M13
GND	M22
GND	N10
GND	N11
GND	N12
GND	N13
GND	P14
GND	P9
GND	R15
GND	R8
GND	U16
GND	U6
GND	V18
GND	V5
GND	W19
GND	W4
GND	Y20
GND	Y3
GND/LP	G7
NC	A17
NC	A18

FG484	
AX500 Function	Pin Number
IO54PB2F5	H22
IO55NB2F5	L17
IO55PB2F5	K17
IO56NB2F5	K21
IO56PB2F5	K22
IO58NB2F5	L20
IO58PB2F5	K20
IO59NB2F5	L18
IO59PB2F5	K18
IO60NB2F5	M21
IO60PB2F5	L21
IO61NB2F5	L16
IO61PB2F5	K16
IO62NB2F5	M19
IO62PB2F5	L19
Bank 3	
IO63NB3F6	N16
IO63PB3F6	M16
IO64NB3F6	P22
IO64PB3F6	N22
IO65NB3F6	N20
IO65PB3F6	M20
IO66NB3F6	P21
IO66PB3F6	N21
IO67NB3F6	N18
IO67PB3F6	N19
IO68NB3F6	T22
IO68PB3F6	R22
IO69NB3F6	N17
IO69PB3F6	M17
IO70NB3F6	T21
IO70PB3F6	R21
IO71NB3F6	P18
IO71PB3F6	P19
IO72NB3F6	R20

FG484	
AX500 Function	Pin Number
IO72PB3F6	P20
IO73PB3F6	R19
IO74NB3F7	V21
IO74PB3F7	U21
IO75NB3F7	V22
IO75PB3F7	U22
IO76NB3F7	U20
IO76PB3F7	T20
IO77NB3F7	R17
IO77PB3F7	P17
IO78NB3F7	W21
IO78PB3F7	W22
IO79NB3F7	T18
IO79PB3F7	R18
IO80NB3F7	W20
IO80PB3F7	V20
IO81NB3F7	U19
IO81PB3F7	T19
IO82NB3F7	U18
IO82PB3F7	V19
IO83NB3F7	R16
IO83PB3F7	P16
Bank 4	
IO84NB4F8	AB18
IO84PB4F8	AB19
IO85NB4F8	T15
IO85PB4F8	T16
IO86NB4F8	AA18
IO86PB4F8	AA19
IO87NB4F8	W17
IO87PB4F8	V17
IO88NB4F8	Y19
IO88PB4F8	W18
IO89NB4F8	U14
IO89PB4F8	U15

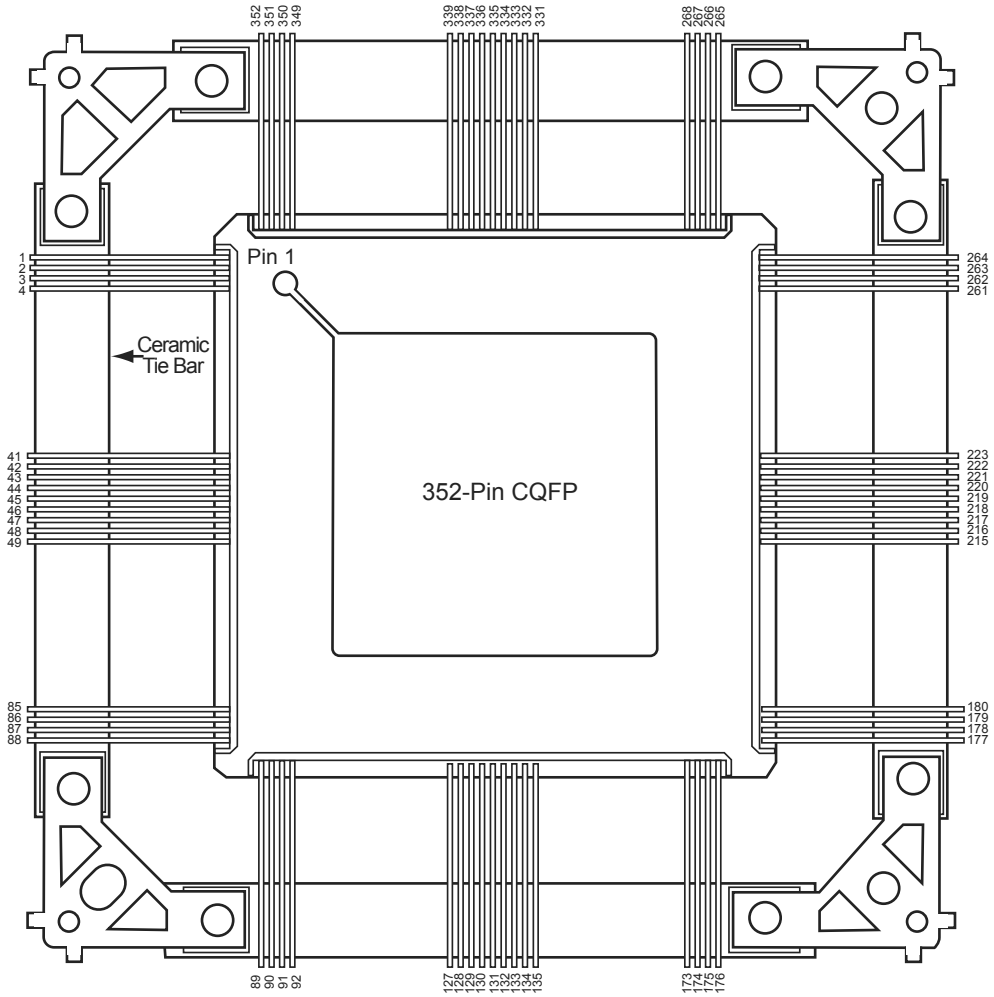
FG484	
AX500 Function	Pin Number
IO90NB4F8	Y17
IO90PB4F8	Y18
IO91NB4F8	V15
IO91PB4F8	V16
IO92PB4F8	AB17
IO93NB4F8	Y15
IO93PB4F8	Y16
IO94NB4F9	AA16
IO94PB4F9	AA17
IO95NB4F9	AB14
IO95PB4F9	AB15
IO96NB4F9	W15
IO96PB4F9	W16
IO97NB4F9	AA13
IO97PB4F9	AB13
IO98NB4F9	AA14
IO98PB4F9	AA15
IO100NB4F9	Y14
IO100PB4F9	W14
IO101NB4F9	Y12
IO101PB4F9	Y13
IO102NB4F9	AA11
IO102PB4F9	AA12
IO103NB4F9/CLKEN	V12
IO103PB4F9/CLKEP	V13
IO104NB4F9/CLKFN	W11
IO104PB4F9/CLKFP	W12
Bank 5	
IO105NB5F10/CLKGN	U10
IO105PB5F10/CLKGP	U11
IO106NB5F10/CLKHN	V9
IO106PB5F10/CLKHP	V10
IO107NB5F10	Y10
IO107PB5F10	Y11
IO108NB5F10	AA9

FG896	
AX1000 Function	Pin Number
IO206PB6F19	AB4
IO207NB6F19	W6
IO207PB6F19	W7
IO208NB6F19	AB3
IO208PB6F19	AC3
IO209NB6F19	V8
IO209PB6F19	V9
IO210NB6F19	AA2
IO210PB6F19	AA1
IO211NB6F19	V5
IO211PB6F19	W5
IO212NB6F19	Y3
IO212PB6F19	Y4
IO213NB6F19	V7
IO213PB6F19	V6
IO214NB6F20	W3
IO214PB6F20	W4
IO215NB6F20	U8
IO215PB6F20	U9
IO216NB6F20	W1
IO216PB6F20	W2
IO217NB6F20	U7
IO217PB6F20	U6
IO218NB6F20	U4
IO218PB6F20	V4
IO219NB6F20	T5
IO219PB6F20	U5
IO220NB6F20	U3
IO220PB6F20	V3
IO221NB6F20	T8
IO221PB6F20	T9
IO222NB6F20	U2
IO222PB6F20	V2
IO223NB6F20	T7
IO223PB6F20	T6

FG896	
AX1000 Function	Pin Number
IO224NB6F20	R2
IO224PB6F20	T2
Bank 7	
IO225NB7F21	R7
IO225PB7F21	R6
IO226NB7F21	R4
IO226PB7F21	R5
IO227NB7F21	R8
IO227PB7F21	R9
IO228NB7F21	P1
IO228PB7F21	R1
IO229NB7F21	P9
IO229PB7F21	P8
IO230NB7F21	N2
IO230PB7F21	P2
IO231NB7F21	P7
IO231PB7F21	P6
IO232NB7F21	N3
IO232PB7F21	P3
IO233NB7F21	P4
IO233PB7F21	P5
IO234NB7F21	L1
IO234PB7F21	M1
IO235NB7F21	M4
IO235PB7F21	N4
IO236NB7F22	N7
IO236PB7F22	N6
IO237NB7F22	N8
IO237PB7F22	N9
IO238NB7F22	M5
IO238PB7F22	N5
IO239NB7F22	L2
IO239PB7F22	M2
IO240NB7F22	L3
IO240PB7F22	M3

FG896	
AX1000 Function	Pin Number
IO241NB7F22	M8
IO241PB7F22	M7
IO242NB7F22	K4
IO242PB7F22	L4
IO243NB7F22	L6
IO243PB7F22	M6
IO244NB7F22	K5
IO244PB7F22	L5
IO245NB7F22	J4
IO245PB7F22	J3
IO246NB7F22	G2
IO246PB7F22	H2
IO247NB7F23	L8
IO247PB7F23	L7
IO248NB7F23	G3
IO248PB7F23	H3
IO249NB7F23	G4
IO249PB7F23	H4
IO250NB7F23	J6
IO250PB7F23	K6
IO251NB7F23	H5
IO251PB7F23	J5
IO252NB7F23	F2
IO252PB7F23	F1
IO253NB7F23	K8
IO253PB7F23	K7
IO254NB7F23	F4
IO254PB7F23	F3
IO255NB7F23	G6
IO255PB7F23	H6
IO256NB7F23	F5
IO256PB7F23	G5
IO257NB7F23	H7
IO257PB7F23	J7
Dedicated I/O	

CQ352



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

CQ352	
AX500 Function	Pin Number
GND	21
GND	27
GND	33
GND	39
GND	45
GND	51
GND	57
GND	63
GND	69
GND	75
GND	81
GND	88
GND	89
GND	97
GND	103
GND	109
GND	115
GND	121
GND	133
GND	145
GND	151
GND	157
GND	163
GND	169
GND	176
GND	177
GND	186
GND	192
GND	198
GND	204
GND	210
GND	216
GND	222
GND	228
GND	234

CQ352	
AX500 Function	Pin Number
GND	240
GND	246
GND	252
GND	258
GND	264
GND	265
GND	274
GND	280
GND	286
GND	292
GND	298
GND	310
GND	322
GND	330
GND	334
GND	340
GND	345
GND/LP	352
NC	91
NC	117
NC	130
NC	131
NC	148
NC	174
NC	268
NC	294
NC	307
NC	308
NC	327
NC	328
PRA	312
PRB	311
PRC	135
PRD	134
TCK	349

CQ352	
AX500 Function	Pin Number
TDI	348
TDO	347
TMS	350
TRST	351
VCCA	3
VCCA	14
VCCA	32
VCCA	56
VCCA	74
VCCA	87
VCCA	102
VCCA	114
VCCA	150
VCCA	162
VCCA	175
VCCA	191
VCCA	209
VCCA	233
VCCA	251
VCCA	263
VCCA	279
VCCA	291
VCCA	329
VCCA	339
VCCDA	2
VCCDA	44
VCCDA	90
VCCDA	116
VCCDA	132
VCCDA	149
VCCDA	178
VCCDA	221
VCCDA	266
VCCDA	293
VCCDA	309

Revision	Changes	Page
Revision 10 (continued)	The "TRST" section was updated.	2-107
	The "Global Set Fuse" section was added.	2-109
	A footnote was added to "FG896" for the AX2000 regarding pins AB1, AE2, G1, and K2.	3-52
	Pinouts for the AX250, AX500, and AX1000 were added for "CQ352".	3-98
	Pinout for the AX1000 was added for "CG624".	3-115
Revision 9 (v2.1)	Table 2-79 was updated.	2-69
	The "Low Power Mode" section was updated.	2-106
Revision 8 (v2.0)	Table 1 has been updated.	i
	The "Ordering Information" section has been updated.	ii
	The "Device Resources" section has been updated.	ii
	The "Temperature Grade Offerings" section is new.	iii
	The "Speed Grade and Temperature Grade Matrix" section has been updated.	iii
	Table 2-9 has been updated.	2-12
	Table 2-10 has been updated.	2-12
	Table 2-1 has been updated.	2-1
	Table 2-2 has been updated.	2-1
	Table 2-3 has been updated.	2-2
	Table 2-4 has been updated.	2-3
	Table 2-5 has been updated.	2-4
	The "Power Estimation Example" section has been updated.	2-5
	The "Thermal Characteristics" section has been updated.	2-6
	The "Package Thermal Characteristics" section has been updated.	2-6
	The "Timing Characteristics" section has been updated.	2-7
	The "Pin Descriptions" section has been updated.	2-9
	Timing numbers have been updated from the "3.3 V LVTTL" section to the "Timing Characteristics" section. Many AC Loads were updated as well.	2-25 to 2-59
	Timing characteristics for the "Hardwired Clocks" and "Routed Clocks" sections were updated.	2-66, 2-68
	Table 2-89 to Table 2-92 and Table 2-98 to Table 2-99 were updated.	2-90 to 2-93, 2-102 to 2-103
	The following sections were updated: "Low Power Mode", "Interface", "Data Registers (DRs)", "Security", "Silicon Explorer II Probe Interface", and "Programming"	2-106 to 2-110
	In the "PQ208" (AX500) section, pins 2, 52, and 156 changed from V_{CCDA} to V_{CCA}. For pins 170 and 171, the I/O names refer to pair 23 instead of 24.	3-84